



## BASEBAND UNITS AND OPTICAL TRANSPORT

## ENABLING FRONTHAUL TO BACKHAUL AND BEYOND

Our base station and optical transport connectivity solutions address the demands of the always-on edge of expanding wireless infrastructure. Along with increased capacity demands driven by the explosion of cloud and connected device growth, engineers need interconnects that enhance the design, implementation and maintenance of networks from the access point to the core. Our innovations in connectivity technologies push the boundaries of speed and bandwidth within today's architectures and address challenging data rate, signal and power requirements of the emerging 5G mobile networks. TE Connectivity's (TE) solutions also include antenna expertise and high-speed board-to-board as well as cabled interconnects offering increased bandwidth for backplanes and midplanes.

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## INPUT/OUTPUT (I/O) POWER INTERNAL INTERCONNECTS **CABLE ASSEMBLIES** I/O performance is the top priority From bus bar to cable, hot-TE's latest high-speed, high-density interconnects support a range of Supporting the latest standards for metro & core networks. Maximize pluggability and blind matingfunctions for the latest BBU and OT designs. and engineered for 25 Gbps and your density & speed with TE's we offer robust power solutions for beyond. Custom solutions available. pluggable I/O connector and cages almost any design configuration. **5G** RF Connectors which support standard interfaces Fine Pitch Board-to-Board (BTB) A wide array of RF for data rates up to 100G. Pluggable I/O and standard coax **Open Compute** 0.4 mm pitch plus **Cable Assemblies** Project (OCP) new shielded boardconnectors for any size TE's high speed (5G) RJ45 Connectors Power Connectors to-FPC solution. base station. pluggable I/O copper Our jacks and plugs The only solution fully cable assemblies are offer reliable and space compatible with the engineered for 25 Gbps and beyond. saving solutions for Open Rack V1 and V2 specifications. flexible and time-saving Free Height Flexible Printed installation, even in harsh environments. Connectors Circuit (FPC) **ELCON Mini** 5G These versatile Space-saving, angled 56 FullAXS Mini Connectors connectors are insertion connectors These interconnects Connectors 5G SFP/SFP+ useful for downsizing that can be placed in provide confidence in Next generation WiMAX a wide range of PCB locations. applications that require parallel system performance and x-TTA connectivity Connectors stacked circuit boards. SFP+ interconnect with their low resistance, highly designs require slim system supports reliable interface. but rugged and easy-to-install cable data rates of 10 assemblies for outdoor use. Gbps signal speeds and is backward M.2 NGEE Connectors RAPID LOCK compatible with SFP. Many cage Save more than 20% Connectors configurations offered provide of PCB real estate No install tools excellent shielding options. compared to the PCI required for this fast, Express Mini Card. reliable replacement for power lugs. G QSFP/zQSFP+ Connectors **CROWN CLIP** Z-PACK Slim UHD Our guad small form Senior High-Speed factor pluggable Offers a low insertion/ Connectors (QSFP) portfolio of extraction force for Designed to be among **SENSORS** SOCKETS interconnects offers a large range high-current mating the densest connectors of simple and customizable design directly to a power bus bar. with the smallest possible footprint to options. State-of-the-art measurement A range of leading IC sockets and free up valuable PCB space. robust memory sockets allows solutions for increased control. **CROWN CLIP** designers to find the best products Junior for their system. RJ point five Board Level Space efficient hot **Humidity Sensors** Connectors Shielding (BLS) **HALLEON** pluggable design for Maintain optimal and This next-gen EMI shields that 5G Land Grid Array AAAAAAA power supply and efficient environments Ethernet link offers minimize crosstalk distribution applications. (LGA) Sockets for people and higher density in tightly designed Socket technology equipment. solutions for a competitive total systems. for microprocessor cost of ownership per port. **Pluggable Bus Bar** packages up to 3647 Cable Assemblies positions. Provides efficient **Temperature Sensors** and reliable power Accurate temperature distribution and quick 50 DDR4 DIMM monitoring for energy installation in a plug-and-play design. efficiency. Connectors Space savings, reduced height, Wave Crimp improved power Versatile solution consumption, and higher data rates designed for higher than the DDR3. power needs. Able to bend through tight spaces; well suited to accommodate the shift from PCB to cable or bus bar te.com/BBU These solutions are helping to unlock the (5**G**)

potential of 5G. Our portfolio of 5G solutions

by design engineers around the world.\*

and capabilities address key challenges faced

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\*5G ready solutions may vary within a product family. Please refer to te.com or contact your TE sales representative for additional information.